

1.) A 1000 liter/sec turbo pump is used to pump a process chamber. It is connected to a large vacuum chamber (infinite conductance) through a tube that is 2 feet long and has an inner diameter of 4 inches. What is its effective pumping speed in liters/sec.

A turbopump is a high or ultrahigh vacuum pump. Thus the worst case vacuum is 10^{-4} torr. Thus, the mean free path between collisions is,

$$\lambda = \frac{kT}{\sqrt{2}\pi d^2 P} = \frac{(1.381e-23 \text{ JK}^{-1})300K}{\sqrt{2}\pi (3e-10)^2 (1e-4 \text{ Torr} \times 133 \text{ Pa} / \text{Torr})} = 0.78 \text{ meters} = 78 \text{ cm}$$

Thus, the Knudsen number is $78 / (2.54 \text{ cm per inch} \times 4 \text{ inches}) = 1.28$ which is greater than 1 indicating molecular flow. Thus,

$$\frac{1}{S_{\text{effective}}} = \frac{1}{1000 \text{ liters} / \text{Sec}} + \frac{1}{11.6 \frac{(4" \times 2.54)^3}{(24" \times 2.54)}} = \frac{1}{1000 \text{ liters} / \text{Sec}} + \frac{1}{200 \text{ liters} / \text{Sec}} = 166 \text{ liters} / \text{sec}$$

2.) A process gas is to introduced into the chamber from problem 1 and the chamber must be maintained at $1e-4$ torr. A.) What is the maximum flow rate (in sccm) of gas the pumping system can handle? B.) Repeat the problem for the pump connected directly to the chamber.

Use $Q=SP$: $Q = (166 \text{ liters/S})(1e-4 \text{ Torr}) = 0.0166 \text{ Torr Liters/Sec}$ or 1.31 sccm (see your conversion chart)

If the pump were connected directly to the chamber, $Q = (1000 \text{ liters/second})(1e-4 \text{ torr}) \Rightarrow 7.9 \text{ sccm}$.

Homework #6:

3.) A wet chemical etch is desired that will etch a via hole through a silicon wafer for integration into a low inductance, high frequency circuit. If a 482 $\mu\text{m}/\text{min}$ etch rate is desired, what is the volume ratios of hydrofluoric, nitric and acetic acids required?

Many possible solutions exist. From the etching triangle, one solution is; $\sim 65\%$ HF, $\sim 25\%$ Nitric, and $\sim 10\%$ Acetic. Two lines are freely drawn parallel to the counterclockwise adjacent triangle side. The third line is constrained to the vertex of the previous 2 lines.

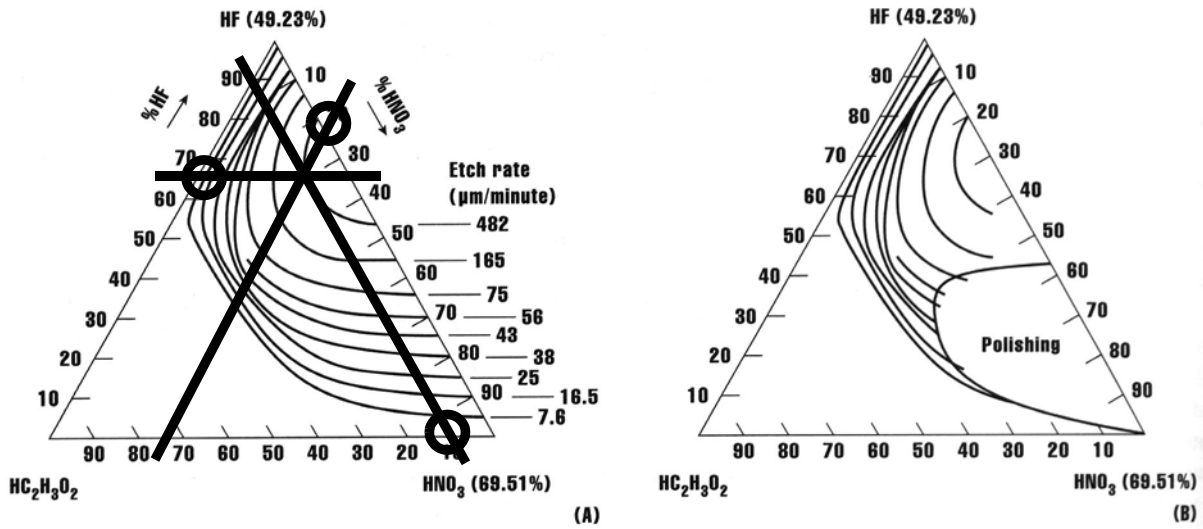


Figure 11-5 The etch rate of silicon in HF and HNO₃ (after Schwarz and Robbins, reprinted by permission of the publisher, The Electrochemical Society Inc.).